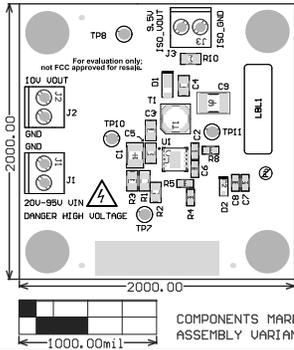


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3,5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4,8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3,5	
7	Bottom Overlay				

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.  
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.  
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.  
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. TO ORDER, REMOVE 'DNP' FROM THE PART NUMBER.  
 ASSEMBLY VARIANT: [No Variations]

**DESIGN INFORMATION**

MIN. TRACK WIDTH: 8 MIL  
 MIN. CLEARANCE: 0.2 mm  
 MIN. VIA PAD SIZE: 24 MIL  
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

**MATERIAL:**  
 FR-408  FR-4 High Tg  OTHER \_\_\_\_\_  
 THICKNESS:  62 MIL (1.6mm) +/-10%  OTHER \_\_\_\_\_  
 TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_  
 BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

**DRILLING:**  
 REFERENCE:  AS SHOWN  NC\_DRILL FILES  
 PTH MIN COPPER THICKNESS:  1MIL  OTHER \_\_\_\_\_

**BOARD FINISH:**  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER \_\_\_\_\_  
 SOLDER RESIST COLOR:  
 GREEN  BLUE  OTHER \_\_\_\_\_

**SURFACE FINISH:**  IMMERSION GOLD (ENG)  ENERP  
 IMM. TIN/SILVER OR EQUIV  OTHER \_\_\_\_\_

**ARRAY/PANEL:**  CUT AND TRIM PER MECH LAYER 1  
 N.C. ROUTE  V. SCORE

**CERTIFICATION:** MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS ->  1  2  3  
 UL 94V-0  RoHS  OTHER PER ORDER

**ADDITIONAL REQUIREMENTS:**  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER  
 MANUFACTURER'S UL:  RAIL  METAL  SILK



PROJECT TITLE:  
LM34927 FLY BUCK CONVERTER

DESIGNED FOR:  
Public Release

FILE NAME:  
PMP11052\_PcbDoc

ENGINEER:  
U. Choudhary

LAYOUT BY:  
K. Nielson

SCALE: 1.00

ALTUM DESIGNER VERSION:  
14.3.14.34663

ADD COMMENTS TO TOP/BOE	A	BOARD #: PMP11052	DATE: 4/22/13	SUN 3:08:10 PM 4/22/13	TEXAS INSTRUMENTS
LAYER NAME = TOP					
PLATT NAME = TOP					

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